MAX232E **DUAL RS-232 DRIVER/RECEIVER** WITH IEC61000-4-2 PROTECTION

SLLS723-APRIL 2006

FEATURES

- Meets or Exceeds TIA/RS-232-F and ITU **Recommendation V.28**
- **Operates From a Single 5-V Power Supply** With 1.0-μF Charge-Pump Capacitors
- Operates up to 120 kbit/s
- Two Drivers and Two Receivers
- ±30-V Input Levels
- Low Supply Current . . . 8 mA Typical
- **ESD Protection for RS-232 Bus Pins**
 - ±15-kV Human-Body Model (HBM)
 - ±8-kV IEC61000-4-2, Contact Discharge
 - ±15-kV IEC61000-4-2, Air-Gap Discharge

D, DW, N, NS, OR PW PACKAGE (TOP VIEW) 16 V_{CC} C1+ 15 GND V_{S+} [] 2 14 DOUT1 C1- [] 3 C2+ [13 RIN1 C2- 1 5 12 ROUT1 11 DIN1 V_{S−} **[**] 6 10 DIN2 DOUT2 7 RIN2 [9 ROUT2

APPLICATIONS

- TIA/RS-232-F
- **Battery-Powered Systems**
- **Terminals**
- **Modems**
- **Computers**

DESCRIPTION/ORDERING INFORMATION

Com.cn The MAX232E is a dual driver/receiver that includes a capacitive voltage generator to supply TIA/RS-232-F voltage levels from a single 5-V supply. Each receiver converts TIA/RS-232-F inputs to 5-V TTL/CMOS levels. This receiver has a typical threshold of 1.3 V, a typical hysteresis of 0.5 V, and can accept ± 30 -V inputs. Each driver converts TTL/CMOS input levels into TIA/RS-232-F levels. The driver, receiver, and voltage-generator functions are available as cells in the Texas Instruments LinASIC™ library.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

MAX232E DUAL RS-232 DRIVER/RECEIVER WITH IEC61000-4-2 PROTECTION

SLLS723-APRIL 2006



ORDERING INFORMATION

T _A	PA	CKAGE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	MAX232ECN	MAX232ECN
	SOIC - D	Tube of 40	MAX232ECD	MAY222FC
	201C – D	Reel of 2500	MAX232ECDR	MAX232EC
0°C to 70°C	SOIC - DW	Tube of 40	MAX232ECDW	MAX232EC
0.0 10 70.0	201C – DW	Reel of 2000	MAX232ECDWR	WIAA232EC
	SOP - NS	Reel of 2000	MAX232ECNSR	Preview
	TCCOD DW	Tube of 25	MAX232ECPW	MAY222FC
	TSSOP – PW	Reel of 2000	MAX232ECPWR	MAX232EC
	PDIP – N	Tube of 25	MAX232EIN	MAX232EIN
	SOIC - D	Tube of 40	MAX232EID	MAY222EI
	30IC - D	Reel of 2500	MAX232EIDR	MAX232EI
−40°C to 85°C	SOIC - DW	Tube of 40	MAX232EIDW	MAX232EI
-40°C 10 65°C	201C – DW	Reel of 2000	MAX232EIDWR	IVIAAZ3ZEI
	SOP - NS	Reel of 2000	MAX232EINSR	Preview
	TSSOP – PW	Tube of 25	MAX232EIPW	MDOOOFI
	13307 - PW	Reel of 2000	MAX232EIPWR	MB232EI

⁽¹⁾ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.





FUNCTION TABLES

Each Driver(1)

INPUT DIN	OUTPUT DOUT
L	Н
Н	L

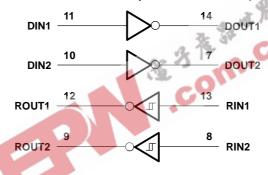
(1) H = high level, L = low level

Each Receiver⁽¹⁾

INPUT RIN	OUTPUT ROUT
L	Н
Н	L

(1) H = high level, L = low level

LOGIC DIAGRAM (POSITIVE LOGIC)



MAX232E DUAL RS-232 DRIVER/RECEIVER WITH IEC61000-4-2 PROTECTION





Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

				MIN	MAX	UNIT
V _{CC}	Input supply voltage range ⁽²⁾			-0.3	6	V
V _{S+}	Positive output supply voltage range			V _{CC} - 0.3	15	V
V _{S-}	Negative output supply voltage range			-0.3	-15	V
	Landadia	Driver		-0.3	V _{CC} + 0.3	
VI	Input voltage range	Receiver			±30	V
	Outsetuallana	DOUT		V _{S-} - 0.3	V _{S+} + 0.3	
Vo	Output voltage range ROUT			-0.3	V _{CC} + 0.3	V
DOUT	Short-circuit duration				Unlimited	
		D package			73	
		DW package			57	
θ_{JA}	Package thermal impedance (3)(4)	N package			67	°C/W
		NS package			64	
		PW package			108	
T _J	Operating virtual junction temperature		- 4-		150	°C
T _{stg}	Storage temperature range		4.15.11	-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltages are with respect to network GND.

Recommended Operating Conditions

			MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage		4.5	5	5.5	V
V _{IH}	High-level input voltage (DIN1, DIN2)		2			V
V _{IL}	Low-level input voltage (DIN1, DIN2)				0.8	V
RIN1, RIN2	Receiver input voltage				±30	V
_	Operating free air temperature	MAX232EC	0		70	۰.
1A	Operating free-air temperature	MAX232EI	-40		85	°C

Electrical Characteristics(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 4)

	PARAMETER	TEST CONDITIONS			TYP ⁽²⁾	MAX	UNIT
I_{CC}	Supply current	$V_{CC} = 5.5 \text{ V},$	All outputs open, T _A = 25°C		8	10	mA

⁽¹⁾ Test conditions are C1–C4 = 1 μ F at V_{CC} = 5 V \pm 0.5 V. (2) All typical values are at V_{CC} = 5 V and T_A = 25°C.

 ⁽³⁾ Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_J(max) – T_A)/θ_{JA}. Operating at the absolute maximum T_J of 150°C can affect reliability.
 (4) The package thermal impedance is calculated in accordance with JESD 51-7.





DRIVER SECTION

Electrical Characteristics(1)

over recommended ranges of supply voltage and operating free-air temperature range

PARAMETER			TEST CON	MIN	TYP ⁽²⁾	MAX	UNIT	
V_{OH}	High-level output voltage	DOUT	$R_L = 3 \text{ k}\Omega \text{ to GND}$		5	7		V
V_{OL}	Low-level output voltage (3)	DOUT	$R_L = 3 \text{ k}\Omega \text{ to GND}$			-7	- 5	V
ro	Output resistance	DOUT	$V_{S+} = V_{S-} = 0,$	$V_O = \pm 2 V$	300			Ω
$I_{OS}^{(4)}$	Short-circuit output current	DOUT	$V_{CC} = 5.5 \text{ V},$	$V_O = 0$		±10		mA
I _{IS}	Short-circuit input current	DIN	V _I = 0				200	μΑ

- (1) Test conditions are C1–C4 = 1 µF at V_{CC} = 5 V ± 0.5 V.
 (2) All typical values are at V_{CC} = 5 V and T_A = 25°C.
 (3) The algebraic convention, in which the least-positive (most negative) value is designated minimum, is used in this data sheet for logic voltage levels only.

 (4) Not more than one output should be shorted at a time.

Switching Characteristics⁽¹⁾

 $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C} \text{ (see Note 4)}$

$v_{CC} = 0$	$V, T_A = 25 C (See Note 4)$	Al .				
	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
SR	Driver slew rate	$R_L = 3 \text{ k}\Omega \text{ to 7 k}\Omega$, See Figure 2			30	V/μs
SR(t)	Driver transition region slew rate	See Figure 3		3		V/μs
	Data rate	One DOUT switching		120		kbit/s

⁽¹⁾ Test conditions are C1–C4 = 1 μF at V_{CC} = 5 V \pm 0.5 V

ESD protection

PARAMETER		TEST CONDITIONS	TYP	UNIT
	1	HBM	±15	kV
DOUT, RIN		IEC61000-4-2, Air-Gap Discharge	±15	kV
		IEC61000-4-2, Contact Discharge	±8	kV

SLLS723-APRIL 2006



RECEIVER SECTION

Electrical Characteristics(1)

over recommended ranges of supply voltage and operating free-air temperature range

	PARAMETER			NDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
V_{OH}	High-level output voltage	ROUT	$I_{OH} = -1 \text{ mA}$		3.5			V
V_{OL}	Low-level output voltage (3)	ROUT	I _{OL} = 3.2 mA				0.4	V
V_{IT+}	Receiver positive-going input threshold voltage	RIN	$V_{CC} = 5 V$,	$T_A = 25^{\circ}C$		1.7	2.4	V
VI_{T-}	Receiver negative-going input threshold voltage	RIN	$V_{CC} = 5 V$,	$T_A = 25^{\circ}C$	0.8	1.2		V
V_{hys}	Input hysteresis voltage	RIN	$V_{CC} = 5 V$		0.2	0.5	1	V
r _i	Receiver input resistance	RIN	$V_{CC} = 5 V$,	T _A = 25°C	3	5	7	kΩ

- (1) Test conditions are C1–C4 = 1 μF at V_{CC} = 5 V ± 0.5 V.
 (2) All typical values are at V_{CC} = 5 V and T_A = 25°C.
 (3) The algebraic convention, in which the least-positive (most negative) value is designated minimum, is used in this data sheet for logic

Switching Characteristics⁽¹⁾

 $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C} \text{ (see Figure 1)}$

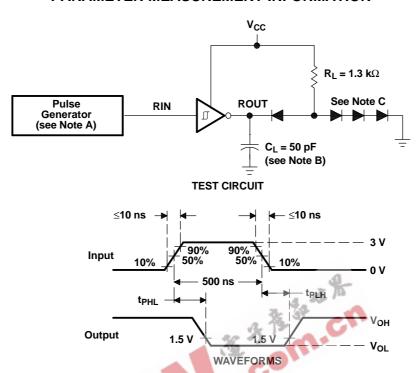
	PARAMETER	4. 15. /11	TYP	UNIT
t _{PLH(R)}	Receiver propagation delay time, low- to high-level output	* 32 C	500	ns
t _{PHL(R)}	Receiver propagation delay time, high- to low-level output	3	500	ns

(1) Test conditions are C1–C4 = 1 μ F at V_{CC} = 5 V \pm 0.5 V.





PARAMETER MEASUREMENT INFORMATION

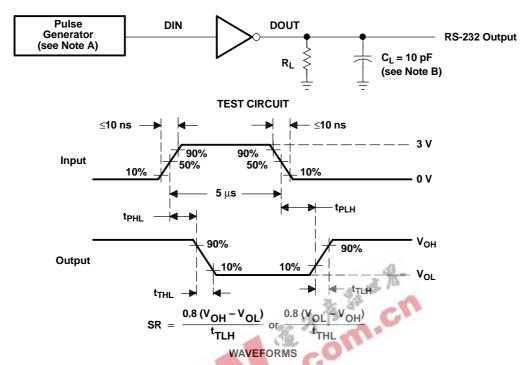


- A. The pulse generator has the following characteristics: $Z_0 = 50 \Omega$, duty cycle $\leq 50\%$.
- B. C_L includes probe and jig capacitance
- C. All diodes are 1N3064 or equivalent.

Figure 1. Receiver Test Circuit and Waveforms for t_{PHL} and t_{PLH} Measurements

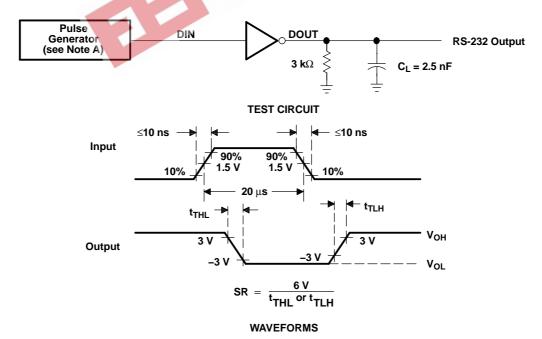


PARAMETER MEASUREMENT INFORMATION (continued)



- A. The pulse generator has the following characteristics: $Z_0 = 50 \Omega$, duty cycle $\leq 50\%$.
- B. C_L includes probe and jig capacitance.

Figure 2. Driver Test Circuit and Waveforms for t_{PHL} and t_{PLH} Measurements (5-μs Input)



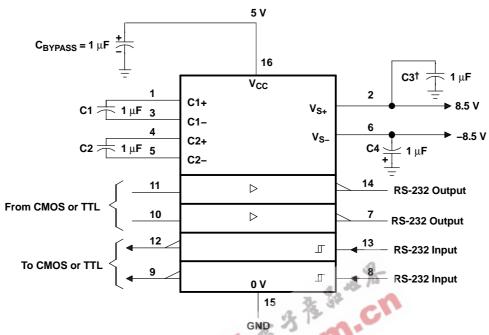
A. The pulse generator has the following characteristics: Z_O = 50 Ω , duty cycle \leq 50%.

Figure 3. Test Circuit and Waveforms for t_{THL} and t_{TLH} Measurements (20- μ s Input)





APPLICATION INFORMATION



 † C3 can be connected to $V_{CC}\, or \, GND.$

- A. Resistor values shown are nominal.
- B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown. In addition to the 1-μF capacitors shown, the MAX232E can operate with 0.1-μF capacitors.

Figure 4. Typical Operating Circuit





6-Dec-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
MAX232ECD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232ECDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232ECDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232ECDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232ECDW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232ECDWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232ECDWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232ECDWRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232ECN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
MAX232ECNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
MAX232ECPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232ECPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232ECPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232ECPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232EID	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232EIDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232EIDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232EIDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232EIDW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232EIDWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232EIDWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232EIDWRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232EIN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
MAX232EINE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
MAX232EIPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM



PACKAGE OPTION ADDENDUM

6-Dec-2006

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins I	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
MAX232EIPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232EIPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX232EIPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

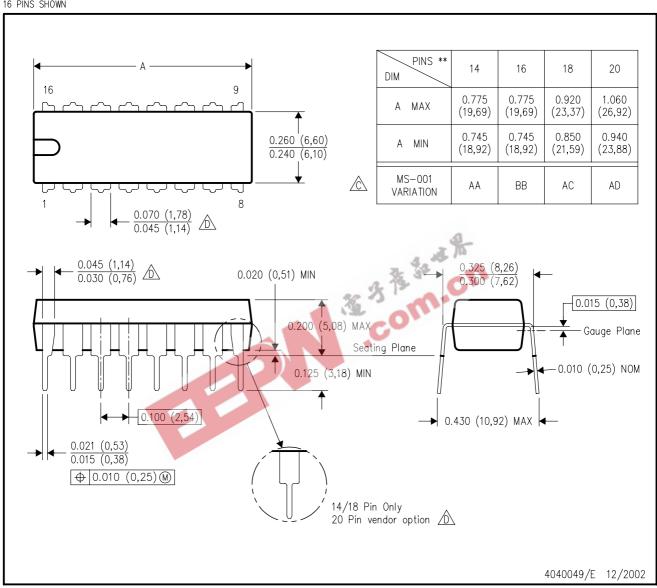
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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

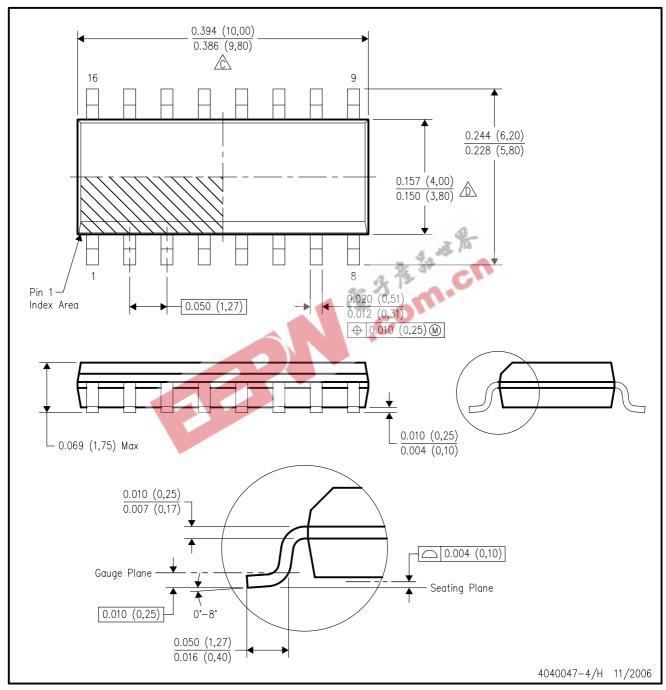


NOTES:

- All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

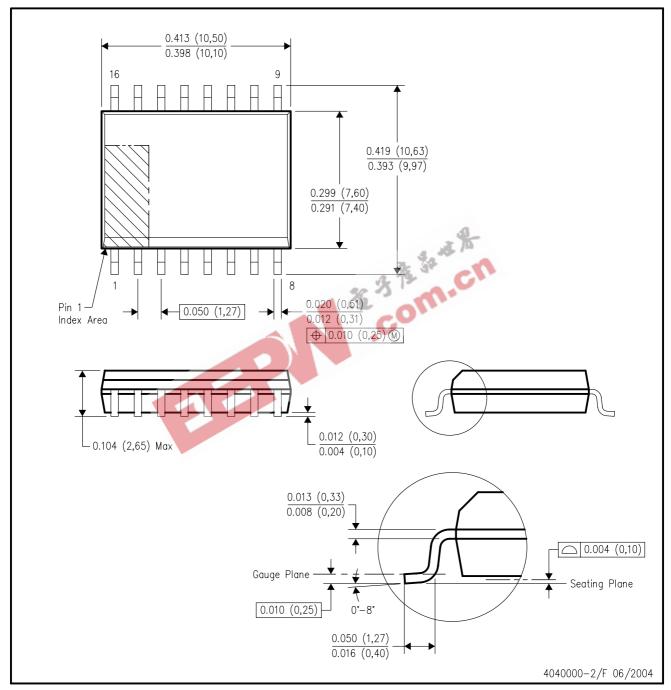
- All linear dimensions are in inches (millimeters).
- A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

 E. Reference JEDEC MS-012 variation AC.



DW (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

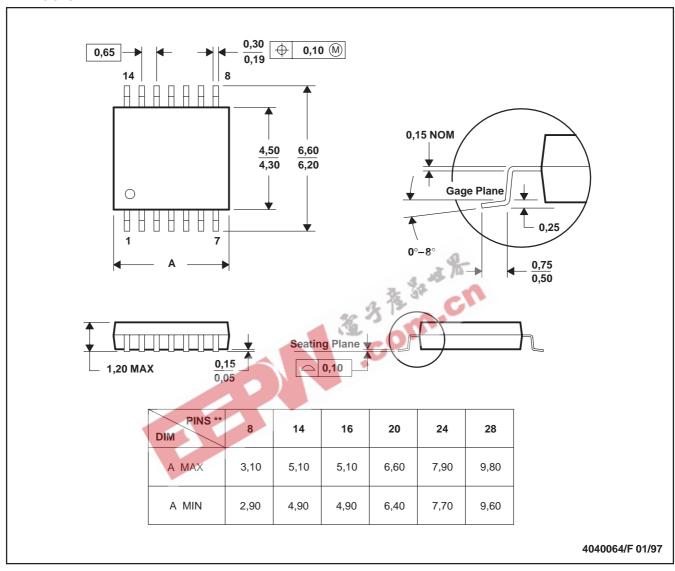
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AA.



PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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